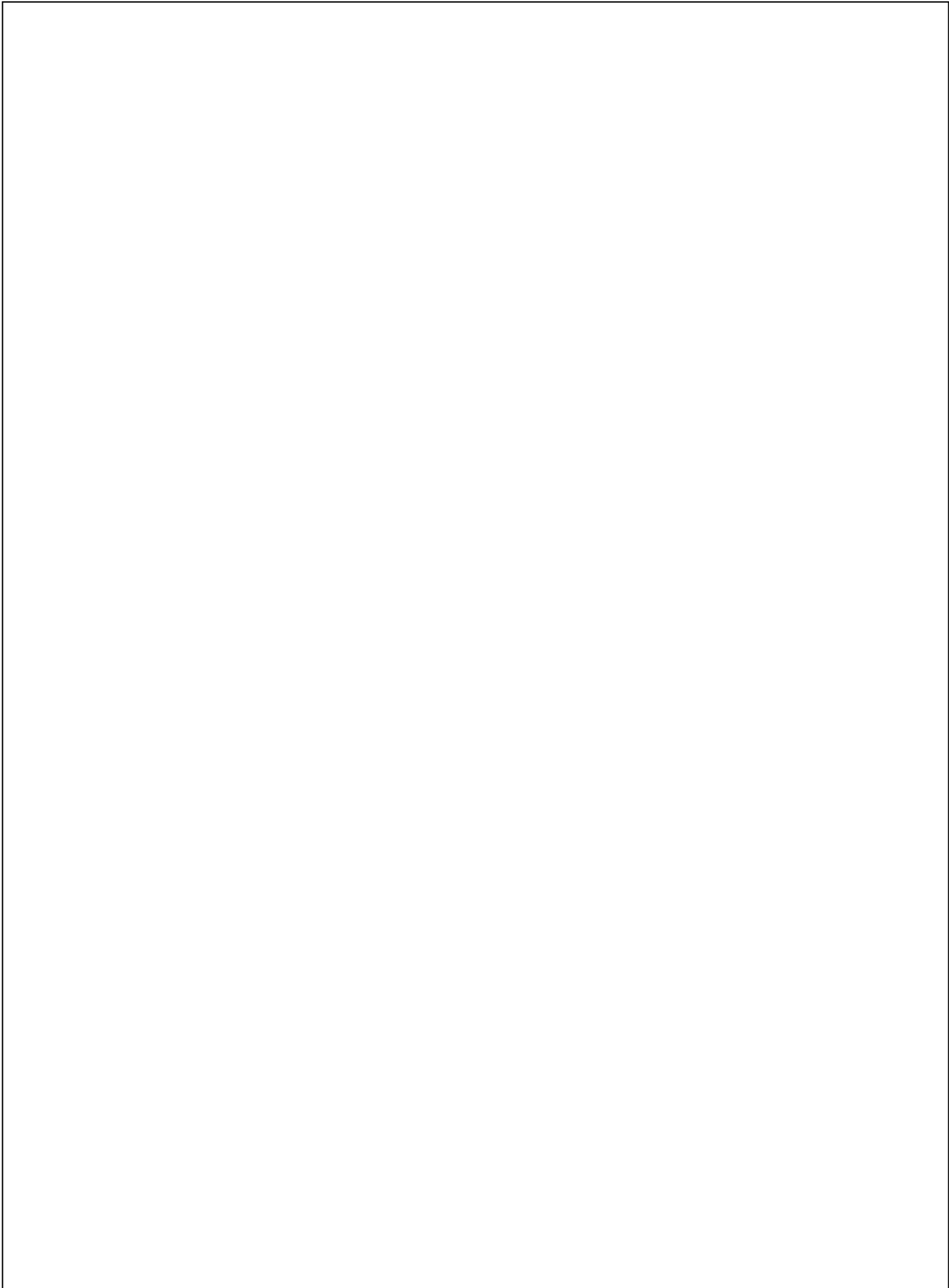


Infrared Photo Diode Specification

- Commodity: Infrared Photo diode
- Intensity Bin Limits (VR=5V, Ee=1mW/cm², λ=940nm)

| BIN CODE | Min.(uA) | Max.(uA) |
|----------|----------|----------|
| 36 | 53 | 64 |
| 37 | 64 | 77 |
| 38 | 77 | 92 |



LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).

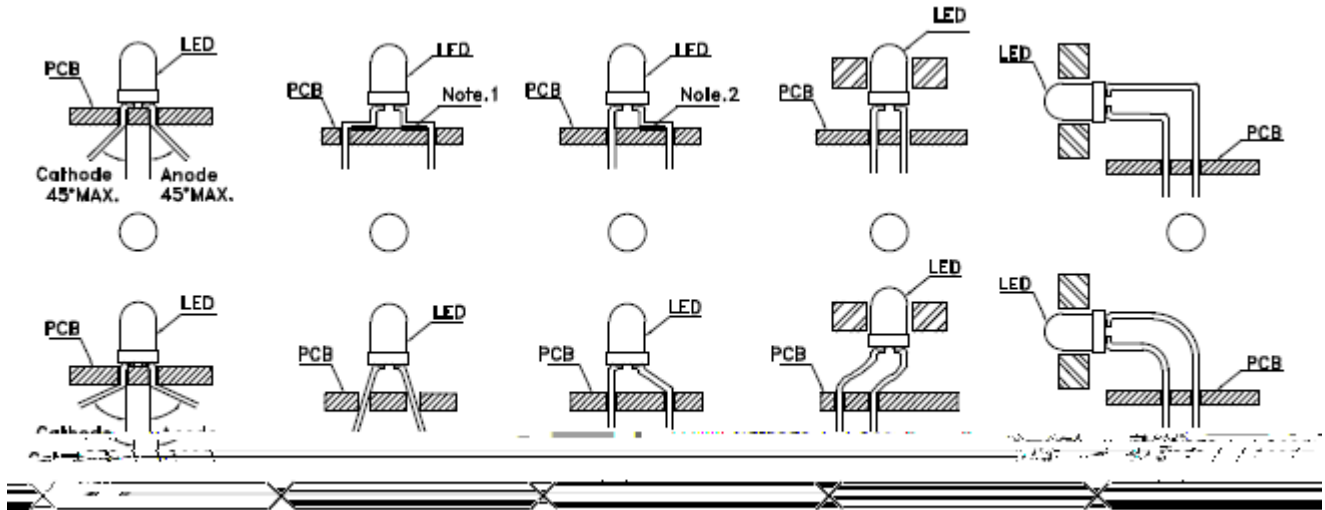


Fig. 1

Mounting method

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

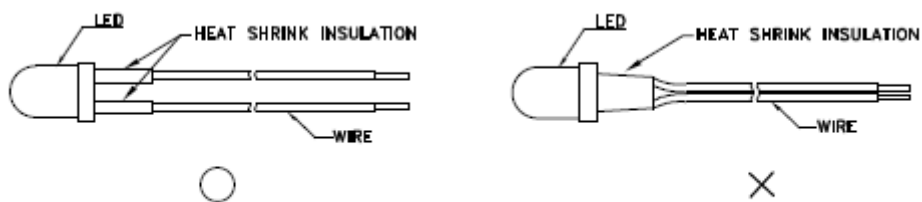


Fig. 2

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.

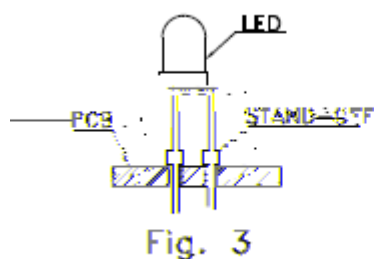


Fig. 3

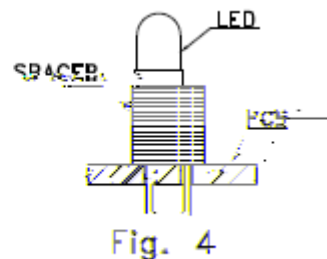
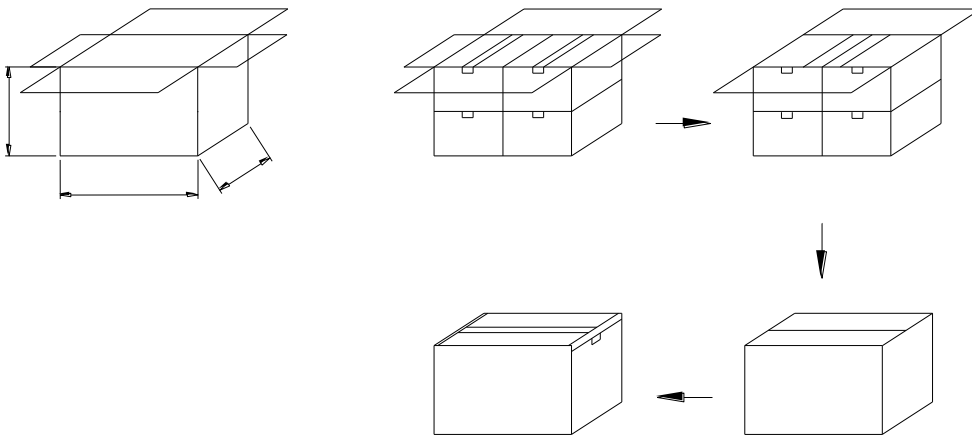
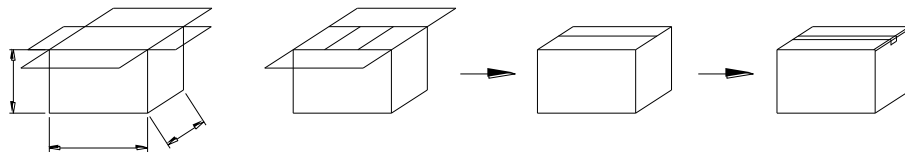
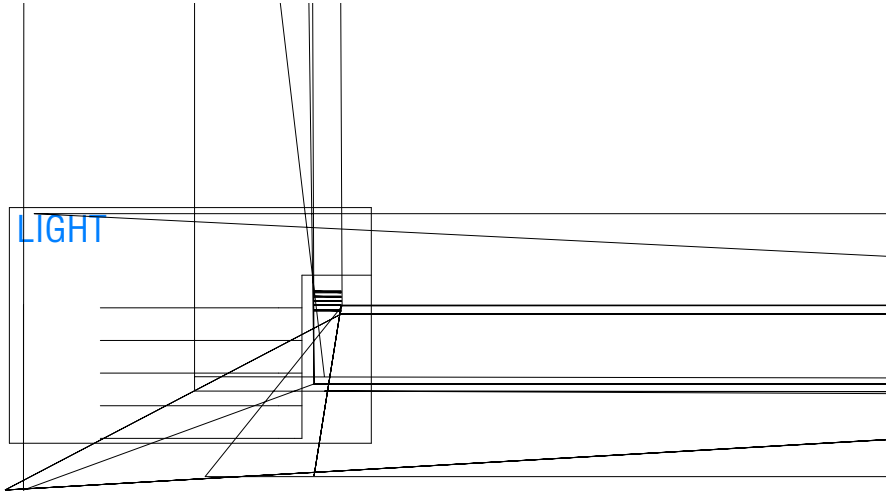


Fig. 4

PACKAGE



| Bag minimum volume (pcs / Bag) | Bag volume (pcs / Bag) | Inner box volume (Bag / box) | Outer carton volume (Box / Carton) |
|-----------------------------------|---------------------------|---------------------------------|---------------------------------------|
| 500 | 1000 | 10 | 4 |